

**Application No.:** 10/074,792  
**Amendment dated:** May 12, 2003  
**Reply to Office Action of:** January 15, 2003

**MAT-6660US2**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claims 1-12. (Cancelled).

Claim 13. (Currently Amended) A multilayer ceramic substrate comprising:

a ceramic substrate;

a first conductive pattern having a convex via having a step, and being formed on said ceramic substrate by a transfer printing technology through an intaglio printing using a flexible resin substance;

an insulation layer formed on said first conductive pattern; and

a second conductive pattern electrically connected by way of said via.

Claim 14. (Currently Amended) A multilayer ceramic substrate comprising:

a ceramic substrate;

a first conductive pattern and a third conductive pattern each having a convex via having a step, and being formed on said ceramic substrate by a transfer printing technology through an intaglio printing using a flexible resin substance;

an insulation layer formed respectively on said first and third conductive patterns; and

a second conductive pattern and a fourth conductive pattern each electrically connected with said first conductive pattern and said third conductive pattern, respectively, by way of said via.

Claim 15. (Previously Amended) The multilayer ceramic substrate of claim 13, wherein a meshed pattern is provided in a part of said conductive pattern.